

# LI WEI

MPhil Student ◇ Department of Computer Science & Engineering  
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## RESEARCH INTERESTS

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- ML in EDA
- Deep Learning using irregular data such as graph and point cloud.

## EDUCATION

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**The Chinese University of Hong Kong, NT, Hong Kong** Aug. 2019 – Aug. 2021(as expected)  
Master of Philosophy, Department of Computer Science and Engineering  
Supervisor: Professor Bei Yu  
GPA: 3.940/4.000

**The Chinese University of Hong Kong, NT, Hong Kong** Aug. 2014 – Aug. 2018  
Bachelor, Department of Computer Science and Engineering  
ELITE Stream student  
Cumulative/Major GPA: 3.529/3.606

## EXPERIENCE

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**NVIDIA, HKSTP, Hong Kong** Nov. 2019 – Present  
AI Technology center internship

**The Chinese University of Hong Kong, NT, Hong Kong** Feb. 2019 – July. 2019  
Research Assistant, Department of Computer Science & Engineering

**Southern University of Science and Technology, Shenzhen, China** June. 2018 – Jan. 2019  
Research Assistant, Department of Computer Science & Engineering

## SELECTED AWARDS AND HONORS

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Richard Newton Young Student Fellowship	DAC	2020
Best Student Paper Award	ICTAI	2019
Distinguished Paper Award	ISSTA	2019
Full Postgraduate Studentship	CUHK	2019-
2nd Place Award in CAD Contest	ICCAD	2018
ELITE Stream Student Scholarship	Faculty of Engineering, CUHK	2018
Admission Scholarship	Soong Ching Ling Foundation	2015-2018
Dean's List	Faculty of Engineering, CUHK	2015,2017,2018
Best Undergraduate Summer Project Award	Faculty of Engineering, CUHK	2017

## PUBLICATIONS

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### Preprint

[J1] **Wei Li**, Yuzhe Ma, Qi Sun, Zhang Lu, Yibo Lin, Iris Hui-Ru Jiang, Bei Yu, David Z. Pan, “OpenMPL: An Open Source Layout Decomposer”, submitted to IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD).

### Conference Papers

[C7] **Wei Li**, Jialu Xia, Yuzhe Ma, Jialu Li, Yibo Lin, Bei Yu, “Adaptive Layout Decomposition with Graph Embedding Neural Networks”, ACM/IEEE Design Automation Conference (**DAC**), San Francisco, July 19-23, 2020.

- [C6] Husheng Zhou, **Wei Li**, Yuankun Zhu, Yuqun Zhang, Bei Yu, Lingming Zhang, Cong Liu, “DeepBillboard: Systematic Physical-World Testing of Autonomous Driving Systems”, ACM/IEEE International Conference on Software Engineering (**ICSE**), Seoul, May 23–29, 2020.
- [C5] Yuzhe Ma, Zhuolun He, **Wei Li**, Tinghuan Chen, Lu Zhang, Bei Yu, “Understanding Graphs in EDA: From Shallow to Deep Learning”, ACM International Symposium on Physical Design (**ISPD**), Taipei, Mar. 25–Apr. 01, 2020. (Invited Paper)
- [C4] Yuzhe Ma, Ran Chen, **Wei Li**, Fanhua Shang, Wenjian Yu, Minsik Cho, Bei Yu, “A Unified Approximation Framework for Deep Neural Networks”, The IEEE International Conference on Tools with Artificial Intelligence (**ICTAI**) 2019. (**Best Student Paper Award**)
- [C3] **Wei Li**, Yuzhe Ma, Qi Sun, Yibo Lin, Iris Hui-Ru Jiang, Bei Yu, David Z. Pan, “OpenMPL: An Open Source Layout Decomposer”, IEEE International Conference on ASIC (**ASICON**), Chongqing, China, Oct. 29–Nov. 1, 2019. (Invited Paper)
- [C2] Xia Li, **Wei Li**, Yuqun Zhang, Yuqun Zhang, Lingming Zhang, “DeepFL: Integrating Multiple Fault Diagnosis Dimensions for Deep Fault Localization”, The ACM SIGSOFT International Symposium on Software Testing and Analysis (**ISSTA**), 2019. (**Distinguished Paper Award**)
- [C1] Bentian Jiang, Xiaopeng Zhang, Ran Chen, Gengjie Chen, Peishan Tu, **Wei Li**, Evangeline F. Y. Young, Bei Yu, “FIT: Fill Insertion Considering Timing”, ACM/IEEE Design Automation Conference (**DAC**), Las Vegas, NV, June 2-6, 2019.

## TECHNICAL SKILLS

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<b>Languages</b>	Mandarin, Cantonese, English
<b>Programming Languages</b>	C/C++, Python, CUDA, $\text{\LaTeX}$